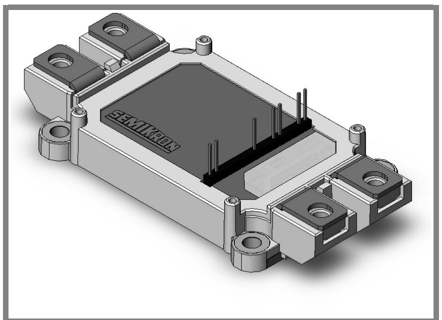
SEMiX 202GB128D



SEMiX^{TM} 2

SPT IGBT Modules

SEMiX 202GB128D

Target Data

Features

- Homogeneous Si
- SPT = Soft-Punch-Through technology
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability

Typical Applications

- AC inverter drives
- UPS
- Electronic Welders f_{sw} up to 20 kHz

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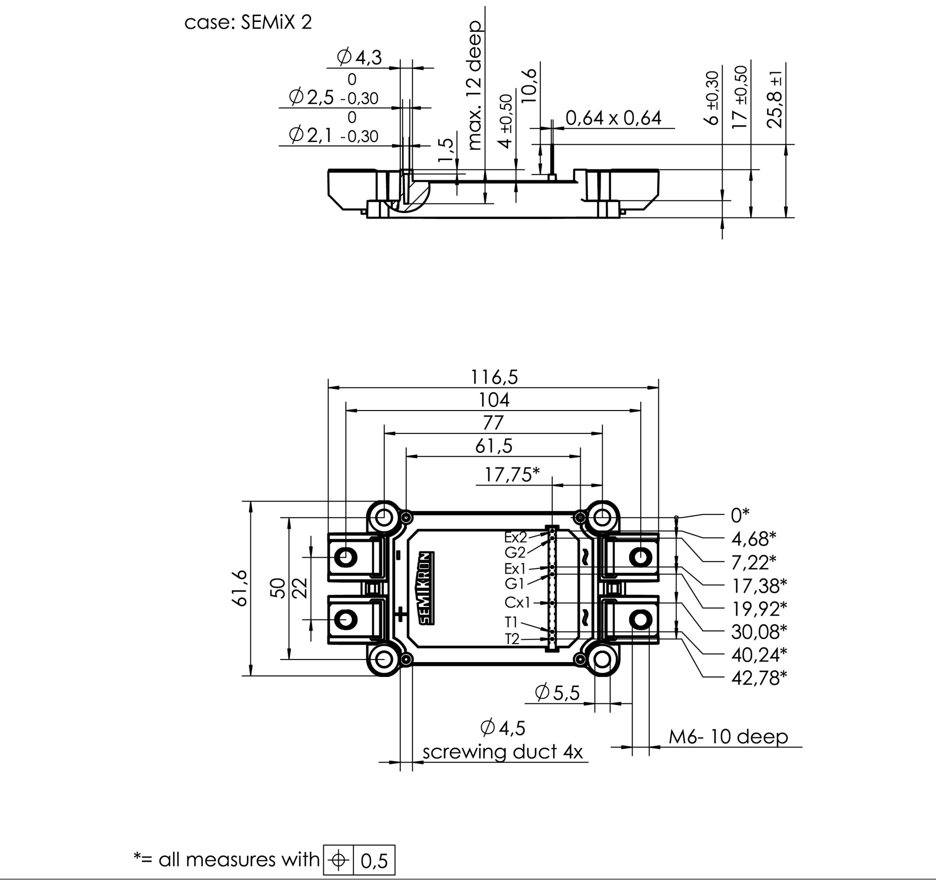
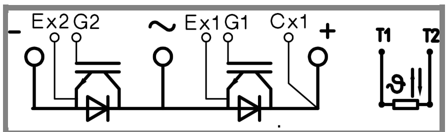
Absolute Maximum Ratings		T_{case} = 25°C, unless otherwise specified	
Symbol	**Conditions**	**Values**	**Units**
IGBT			
V_{CES}		1200	V
I_C	T_c = 25 (80) °C	190 (135)	A
I_{CRM}	T_c = 25 (80) °C, t_p = 1 ms	380 (270)	A
V_{GES}		± 20	V
T_{vj}, (T_{stg})	$T_{OPERATION} \leq T_{stg}$	- 40 ... + 150 (125)	°C
V_{isol}	AC, 1 min.	4000	V
Inverse diode			
I_F = - I_C	T_c = 25 (80) °C	150 (100)	A
I_{FRM}	T_c = 25 (80) °C, t_p = 1 ms	380 (270)	A
I_{FSM}	t_p = 10 ms; sin.; T_j = 25 °C		A

Characteristics				T_{case} = 25°C, unless otherwise specified	
Symbol	**Conditions**	**min.**	**typ.**	**max.**	**Units**
IGBT					
$V_{GE(th)}$	$V_{GE} = V_{CE}$, I_C = 4 mA	4,5	5,5	6,5	V
I_{CES}	V_{GE} = 0, $V_{CE} = V_{CES}$, T_j = 25 (125) °C			0,3	mA
$V_{CE(TO)}$	T_j = 25 (125) °C		1 (0,9)	1,15 (1,05)	V
r_{CE}	V_{GE} = 15 V, T_j = 25 (125) °C		9 (12)	12 (15)	mΩ
$V_{CE(sat)}$	I_C = 100 A, V_{GE} = 15 V, T_j = 25 (125) °C, chip level		1,9 (2,1)	2,35 (2,55)	V
C_{ies}	under following conditions		9		nF
C_{oes}	V_{GE} = 0, V_{CE} = 25 V, f = 1 MHz				nF
C_{res}					nF
L_{CE}			18		nH
$R_{CC'+EE'}$	resistance, terminal-chip, T_c= 25 (125) °C				mΩ
$t_{d(on)}/t_r$	V_{CC} = 600 V, I_C = 100 A				ns
$t_{d(off)}/t_f$	V_{GE} = ± 15 V				ns
E_{on} (E_{off})	$R_{Gon} = R_{Goff}$ = Ω, T_j = 125 °C		8 (11)		mJ
Inverse diode					
$V_F = V_{EC}$	I_F = 100 A; V_{GE} = 0 V; T_j = 25 (125) °C, chip level		2 (1,8)	2,5 (2,3)	V
$V_{(TO)}$	T_j = 25 (125) °C		1,1	1,2	V
r_T	T_j = 25 (125) °C		9	13	mΩ
I_{RRM}	I_F = 100 A; T_j = 25 (125) °C				A
Q_{rr}	di/dt = A/µs				µC
E_{rr}	V_{GE} = 0 V				mJ
Thermal characteristics					
$R_{th(j-c)}$	per IGBT			0,165	K/W
$R_{th(j-c)D}$	per Inverse Diode			0,3	K/W
$R_{th(j-c)FD}$	per FWD				K/W
$R_{th(c-s)}$	per module		0,045		K/W
Temperature sensor					
R_{25}	T_c = 25 °C		5 ±5%		kΩ
$B_{25/85}$	$R_2=R_1\exp[B(1/T_2-1/T_1)]$; T[K];B		3420		K
Mechanical data					
M_s/M_t	to heatsink (M5) / for terminals (M6)	3/2,5		5 /5	Nm
w			236		g



Case SEMiX 2



GB Case SEMiX 2

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

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